

PATENT APPLICATION3/A
7/17/01
M. Prud'homme

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Application No.: U.S. National Stage
of PCT/JP00/05395

Filed: April 16, 2001

Docket No.: 109279

For: INTERCONNECT SUBSTRATE AND METHOD OF MANUFACTURE THEREOF,
ELECTRONIC COMPONENT AND METHOD OF MANUFACTURE THEREOF,
CIRCUIT BOARD AND ELECTRONIC INSTRUMENTPRELIMINARY AMENDMENTDirector of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 12, 19, 21, 22, 31 and 38 as follows:

12. (Amended) The interconnect substrate as defined in claim 1, wherein the first and second substrates are adhered by an anisotropic conductive film including conductive particles.

19. (Amended) The electronic component as defined in claim 15, wherein: an anisotropic conductive film including conductive particles is provided on the surface of the second substrate on which the second interconnect pattern is formed; and the anisotropic conductive film adheres the first substrate to the second substrate, while also electrically connecting the second interconnect pattern to the electronic chip.